

(19)
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(43)

10-2004-0111065
2004 12 31

(21) 10-2004-0044098
(22) 2004 06 15

(30) JP-P-2003-00170428 2003 06 16 (JP)

(71) 가 가 6 7-1

가 가 560

(72) , 560 가 가

, 560 가 가

(74)

:

(54)

(1a, 1c)

(3a)
(5)

(4a)

4a

1A ;

1B 1A ;

2 1 ;

- 3 2 ;
- 4A 2 ;
- 4B 4A ;
- 5A 3 ;
- 5B 5A ;
- 5C ;
- 6 (branch) 가 ;
- 7A ;
- 7B ;
- 7C ;
- 7D ;
- 7E ;
- 7F ;
- 7G

가 가 (ESR) , ,

(valve metal)

2 (manganese dioxide)

, ESR

1A 1B 가 1A 1B ,
 (1) (7), (1), (2), (3), (6)
 (8), (9) (7)
 (resin molding) (encapsulating resin)(10)

1A (3) (2) (6) (8) (9) (10) 가 1B

CPU (power supply circuit) CPU CPU
 ESR (noise) (ripple current) 가 가
 CPU가 (thin profile) ESR
 가 (C_{total}) ESR(ESR_{total})

$$C_{total} = C_1 + C_2 + \dots + C_n \quad (1)$$

$$1/ESR_{total} = 1/ESP_1 + 1/ESP_2 + \dots + 1/ESP_N \quad (2)$$

C_i ESP_i i (i = 1 ~ n) ESR

1A 가 ESR

2001-284192 (1) 1
 1A

2 (1d) 1 (2d) (silver paste) (6) (3c) 2

1 1 2 2
 2003-106565 () 2
 (plate-like)

n) (branched portio

3 (1a 1c) (2a 2c) (1a 1c) (2a 2c) (1a 1c) 2
 (3d) (1a 1c) (2a 2c) (6a)

3 가 (6a) (plate-like shape) 2 (2a
 2c) (1a 1c) (1a 1c) (2a 2c)

() (1a 1c) (3d) 2 (2a 2c) (fillet)
 (6a) (3d) (nugget) (brazing)

가
 가

가

가 ESR

가

(chip-type)

(lead)

(plate-like)
(confronting surfaces)

가

(through hole)

(cutout)

(bonding agent)

가

/

가

(through hole)

(cutout)

가

(anchor effect)

4 (3a) (2a 2c) (4a) (1a 1c) (1a 1c) 2 (1a 1c) (6a) (5)

(die) (cavity) 1A (molded body) 가
 (2a 2c) (7) (2a 2c) (7)

(8) 1A (7)가 (8) 가 , 2
 (8) (1a 1c) (8) , 2

(polythiophene) (polypyrrole) 가 2 (9)
 , ESR

2 (2a 2c) (1a 1c) (3a) (3a) (1a 1c) (eccentric position)
 (5) (4a) (3a) (3a) (solder) (1a 1c)

가 4A (4a) (3a) (4a) (1a 1c) 4B
 (2a 2c) (6a) 4A

(3a) (4a) (4a) 7A 7C
 7A 7B 7C
 7E 7D 7F 7G

5A 5B (1a, 1b 1c) (右端部) 5A 5B (左端 (2a, 2b 2c) (1a, 1b 1c) (2a, 2b 2c) (2a, 2b 2c)
 部), 2b 2c) (1a, 1b 1c) (2a, 2b 2c) (2a, 2b 2c)

3 (6b) 2 3 , 3 3 (2a, 2b 2c)
 (6b) 3 , 3 (2a, 2b 2c)

5B (4b 4c) (3b)가 (1a, 1b) (4b)
 (1b, 1c) 가 (4c) 가 (3b')가
 (3b') 가 5C 가 (3b')가

3 5B 가 가

6 , (3c) (9) (4d) (5) (3c)가
 6 (3c) 가 6 (9) (5) ,
 3c) (3c)가 (4d) (9) (3c) , (,
 , 2 , 가 4A 가 100 4A , 가
 , 2 , 4A 가 100 100 가
 , 2 가 41% 가 41% , ,
 , , 가 , ,

- (57)
1. (sintered body) (chip-type) , (lead) , (plate-like) ; (confronting surface) 가 ; ; (through hole) (cutout)
 2. 1 , (bonding agent) ,
 3. 1 2 , ,

3 4.

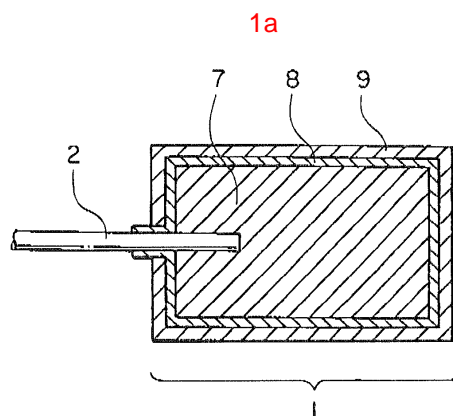
가 ;

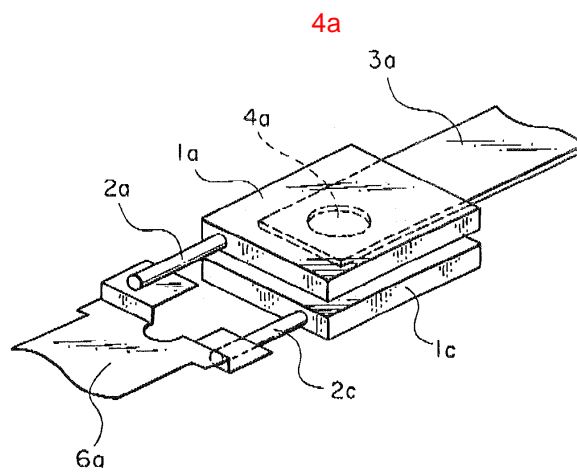
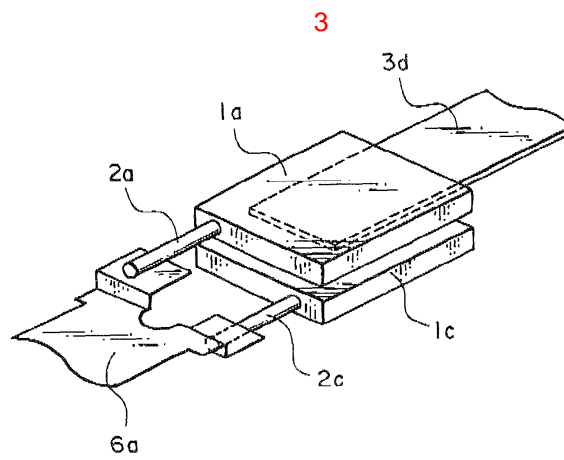
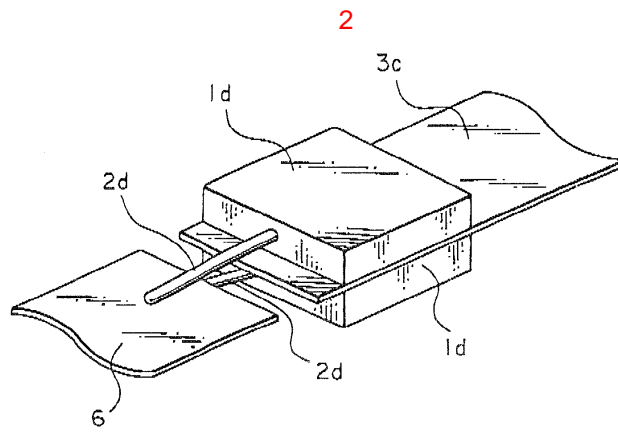
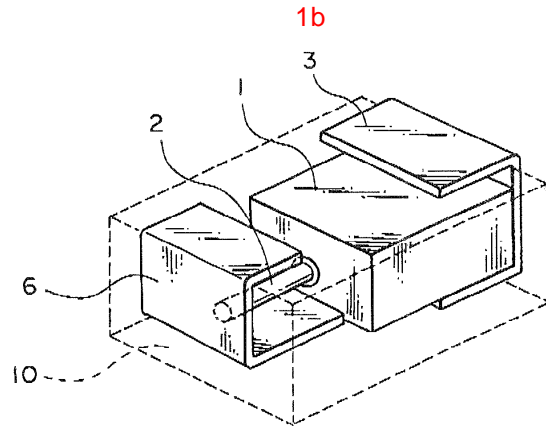
5.

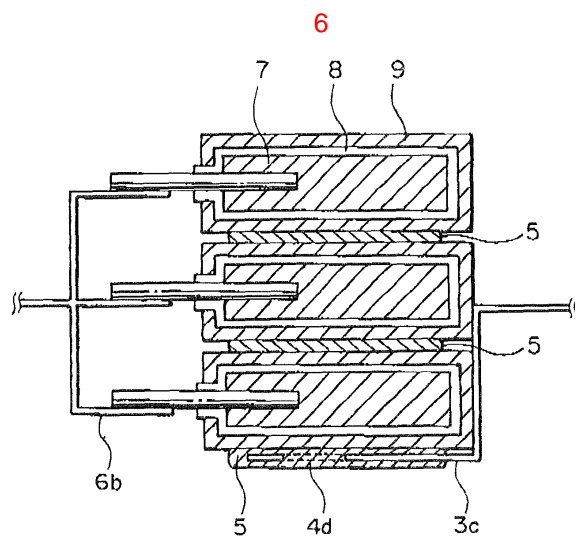
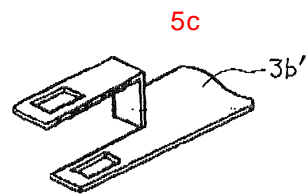
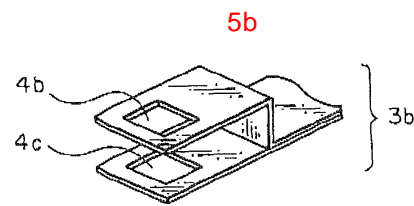
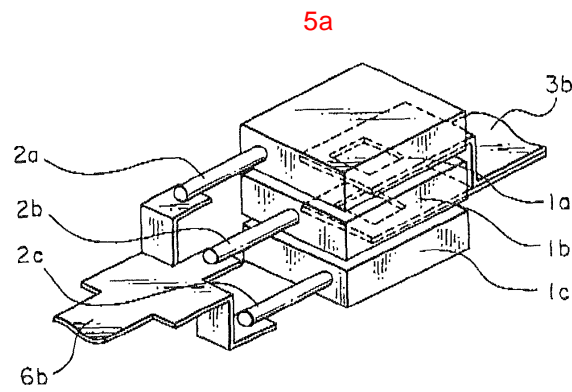
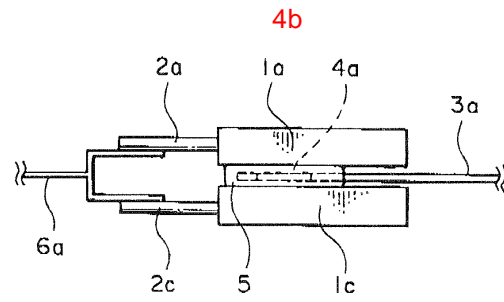
5 6.

가

5 6 7.



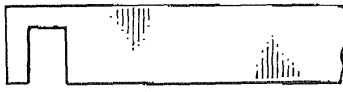




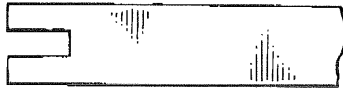
7a



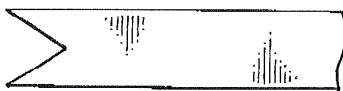
7b



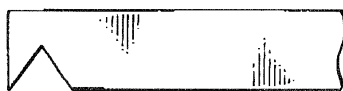
7c



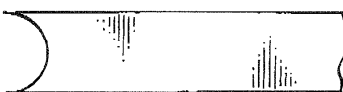
7d



7e



7f



7g

